

3DIC 2024 Program at-a-glance

September 25-27, 2024

Conference Venue:

September 25, 2024 at Hotel Metroplitan Sendai

September 26-27, 2024 at Sendai Kakusai Hotel

as of September 1,

Date	25-Sep-24		26-Sep-24		27-Sep-24			
Venue	Hotel Metropolitan Sendai		Sendai Kokusai Hotel		Sendai Kokusai Hotel		NanoTerasu	
Room	Sendai-East	Sendai-West/South	Heian	Heian & Foyer	Heian	Heian & Foyer	NanoTerasu Visit	
9:00			Registration (8:30-)	Preparation for exhibition and poster session (8:30-10:00)	Registration (8:20-)	Preparation		
			Keynote Talk IV (8:50-9:30)		Keynote Talk V (8:40-9:20)			
10:00			Invited Talk IV (9:30-10:00)	Exhibition (10:00-18:00)	Session 4: Design&Thermal Management (9:20-10:20)	Exhibition (9:00-10:35)		
			Invited Talk V (10:00-10:30)		Coffee Break (10:20-10:35)			
			Coffee Break (10:30-10:45)		Session 5 : Bumpless and Hybrid Bonding Technology (10:35-12:15)	Dismantle by exhibitors (10:35-11:30)		
11:00			Session 2: Process Technology for Hybrid Bonding (10:45-11:45)				Dismantle by organizer (11:30-12:30)	
12:00	Registration (12:00-)		Lunch Time (11:45-13:00)					Award Ceremony & Closing Remarks (12:15-12:30)
13:00	Opening Remark (13:00-13:10)		Poster Session (Core time)	Poster & Exhibition (10:00-18:00)				
	Keynote Talk I (13:10-13:50)							
14:00	Keynote Talk II (13:50-14:30)				Panel Session (14:30-15:15)			NanoTerasu Visit (in Japanese) 14:00-15:00
	Coffee Break (14:30-14:45)				Coffee Break (15:15-15:30)			
15:00	Keynote Talk III (14:45-15:25)		Invited Talk VI (15:30-16:00)			NanoTerasu Visit (in English) 15:00-16:00		
	Invited Talk I (15:25-15:55)		Invited Talk VII (16:00-16:30)					
16:00	Invited Talk II (15:55-16:25)		Session 3: Advanced Interposers (16:30-17:30)					
	Invited Talk III (16:25-16:55)			Session 1 : Quantum Technology (16:45-17:25)				
17:00								
18:00								
19:00		Banquet (18:00-20:00)						
20:00								